Product Change Notification / LIAL-13PAEG321

Date:

16-Feb-2023

Product Category:

High Voltage Power Modules

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6158 Initial Notice: Qualification of MP3B as a new assembly site for selected Microsemi MSCDR45Xxxx, MSCDR90Axxx, MSCGLQ25xxx, MSCGLQ50xxx, MSCGLQ75xxx, and MSCSM120xxx device families available in BL1, BL2 and BL3 packages.

Affected CPNs:

LIAL-13PAEG321_Affected_CPN_02162023.pdf
LIAL-13PAEG321_Affected_CPN_02162023.csv

Notification Text:

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MP3B as a new assembly site for selected Microsemi MSCDR45Xxxx, MSCDR90Axxx, MSCGLQ25xxx, MSCGLQ50xxx, MSCGLQ75xxx, and MSCSM120xxx device families available in BL1, BL2 and BL3 packages.

Pre and Post Change Summary:

	Pre Change	**Post Change**
Assembly Site	Microchip Technology Inc. (MPH2)/ (MPH2)	Microchip Technology Inc. (MPHIL-3)/ (MP3B)

Impacts to Data Sheet: None

Change Impact None

Reason for Change: To improve manufacturability by qualifying MP3B as a new assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: June 2023

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2023					**>**	**June 2023**				
Workweek	05	06	07	08	09		22	23	24	25	26
Initial PCN Issue Date			x								
Qual Report Availability										x	
Final PCN Issue Date										x	

Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 16, 2023: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-13PAEG321_Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

QUALIFICATION PLAN SUMMARY

PCN#: LIAL-13PAEG321

Date:
January 18, 2023

Qualification of MP3B as a new assembly site for selected Microsemi MSCDR45Xxxx, MSCDR90Axxx, MSCGLQ25xxx, MSCGLQ50xxx, MSCGLQ75xxx and MSCSM120xxx device families available in BL1, BL2 and BL3 packages.

Purpose Qualification of MP3B as a new assembly site for selected Microsemi MSCDR45Xxxx, MSCDR90Axxx, MSCGLQ25xxx, MSCGLQ50xxx, MSCGLQ75xxx, and MSCSM120xxx device families available in BL1, BL2 and BL3 packages.

CCB No. 6158

Misc.	Assembly site	MPHIL3
	BD Number	CC7514A-20 ed04 MSCGLQ75DDU120CT BL3NG
	Part Number (CPN)	MSCGLQ75DDU120CT BL3NG
	Assembly Shipping Media (T/R, Tube/Tray)	Anti-static Tube
	Reliability Site	MPHIL3

Test Name	Conditions	Sample Size	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	REL Test Site	Pkg. Type	Special Instructions
Temp Cycle	JESD22-A104. -40°C to +125°C • Ramp at 7°C/min • 15 minutes per cycle for 1000 cycles with cross-section every 250 cycles.	5	1	5	0	12	MPHIL-2	Module	
Isolation Test	• Refer to PI-37311 - Module Isolation Test Specification	100	1	100	0	15	MPHIL-2	Module	
Parametric Test	• Refer to PI-37312 - Module Final Test Specification	100	1	100	0	3	MPHIL-2	Module	
Mechanical Inspection (External Visual)	• As per PI-37305 Module and PSDS Die Sales Visual Inspection Criteria Specification (• As per PI-37310 Module Final Visual Inspection Specification • As per device assembly diagram for mechanical inspection	1	1	1	0	2	MPHIL-3	Module	
Solder Joint Check	• As per PI-37305 Module and PSDS Die Sales Visual Inspection Criteria Specification	100	1	100	0	1	MPHIL-3	Module	
Internal Visual (3rd Optical Inspection)	• As per PI-37323 KPTM/KPTV Module Assembly Specification • As per PI-37305 Module and PSDS Die Sales Visual Inspection Criteria Specification • As per PI-37310 Final Visual Specification Module	100	1	100	0	1	MPHIL-3	Module	

Flatness Check	• As per PI-37358 Module Die/DBC Attach for AlSiC Baseplate Specification (Bordeaux) • As per PI-37305 Module and PSDS Die Sales Visual Inspection • As per PI-37310 Final Visual Specification Module	100	1	100	0	1	MPHIL-3	Module	• Refer to specific device SOW for the Baseplate flatness requirement

LIAL-13PAEG321 - CCB 6158 Initi MSCDR90/ MSCGLQ2! MSCGLQ5(MSCGLQ7! and MSCSI BL2 and BL3 packages.

Affected Catalog Part Numbers(CPN)

MSCDR45X160BL3NG
MSCDR90A160BL1NG
MSCGLQ25X120CRTBL3NG
MSCGLQ50A120CTBL1NG
MSCGLQ50DDU120CTBL2NG
MSCGLQ50DH120CTBL2NG
MSCGLQ50DU120CTBL1NG
MSCGLQ50H120CTBL2NG
MSCGLQ75DDU120CTBL3NG
MSCGLQ75H120CTBL3NG
MSCSM120AM31CTBL1NG
MSCSM120AM31TBL1NG
MSCSM120DAM31CTBL1NG
MSCSM120DDUM16CTBL3NG
MSCSM120DDUM16TBL3NG
MSCSM120DDUM31CTBL2NG
MSCSM120DDUM31TBL2NG
MSCSM120DHM31CTBL2NG
MSCSM120DUM31CTBL1NG
MSCSM120DUM31TBL1NG
MSCSM120HM16CTBL3NG
MSCSM120HM16TBL3NG
MSCSM120HM31CTBL2NG
MSCSM120HM31TBL2NG
MSCSM120SKM31CTBL1NG
MSCSM120XM31RTBL3NG